

Space-EPS* – a space suitable engineering model of an entangled photon source

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Erik Beckert¹, Oliver deVries¹, Christoph Damm¹

Rupert² Ursin, Fabian Steinlechner²

¹*Fraunhofer-Institut für Angewandte Optik und Feinmechanik (IOF)
Albert-Einstein-Strasse 7, 07745 Jena, Germany*

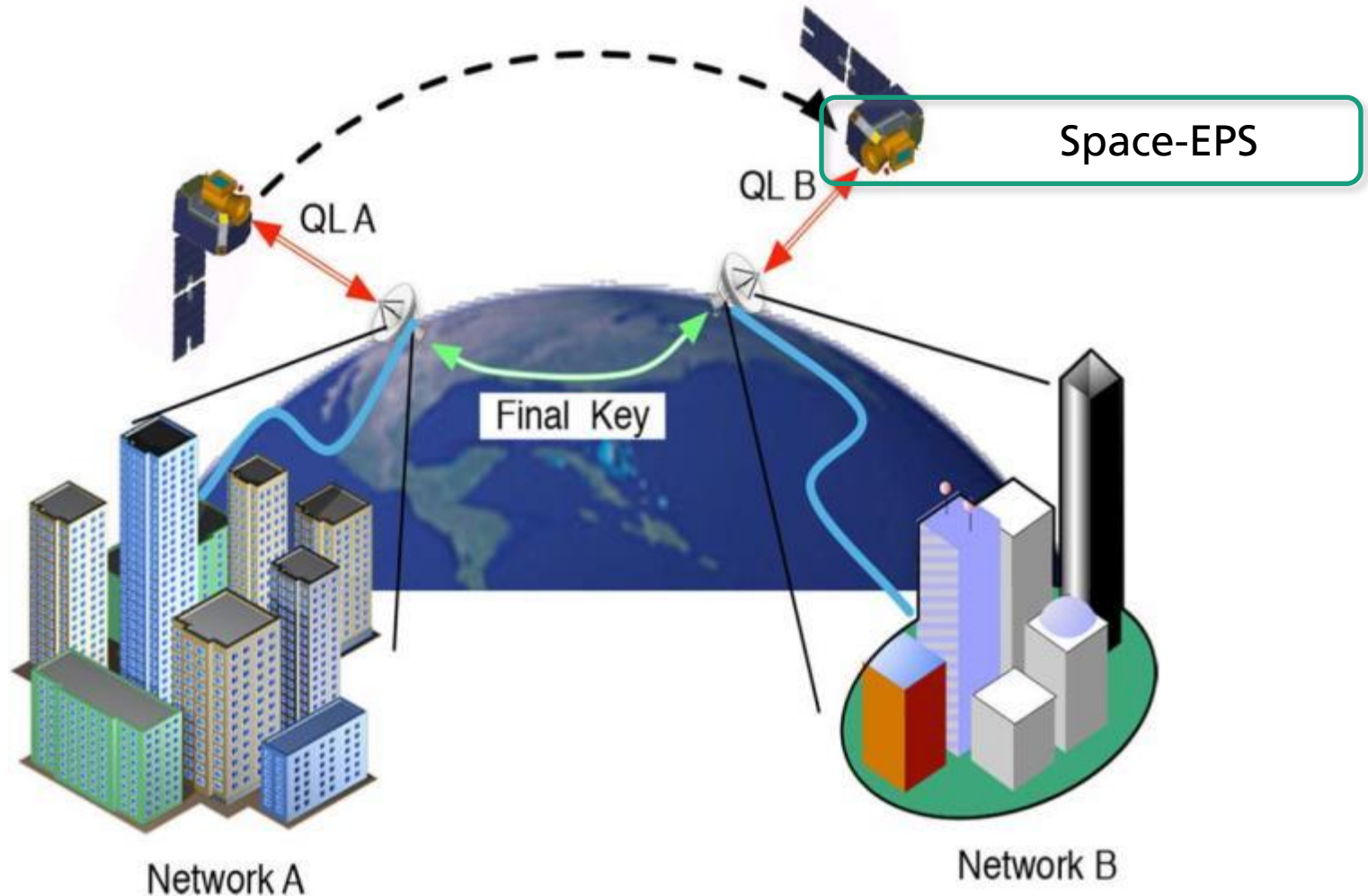
²*Institute for Quantum Optics and Quantum Information – Vienna
Boltzmannngasse 3, 1090 Vienna, Austria*

erik.beckert@iof.fraunhofer.de, +49 3641/807-338

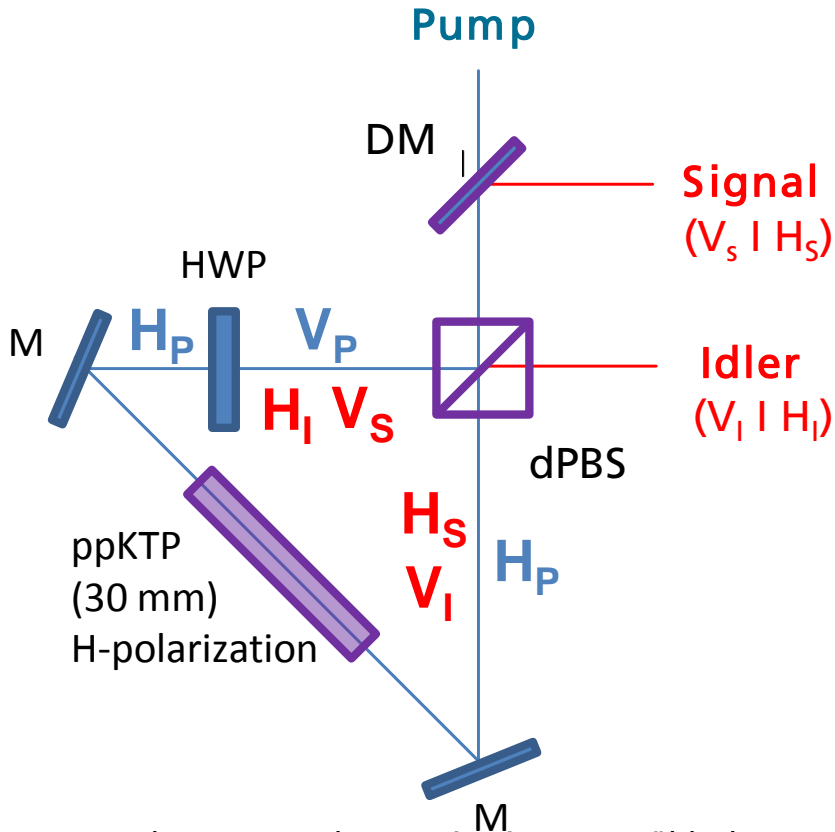


Project Goal

Space-suitable Single-Photon Source for QKD (Space-EPS)



Engineering Approach Requirements



Hybrid setup for polarization entanglement

- Sagnac Interferometer
- Spontaneous parametric down-conversion (SPDC) in bulk periodically poled ppKTP
- Pumped at 405 nm

Space suitable for down- (up-)link configuration

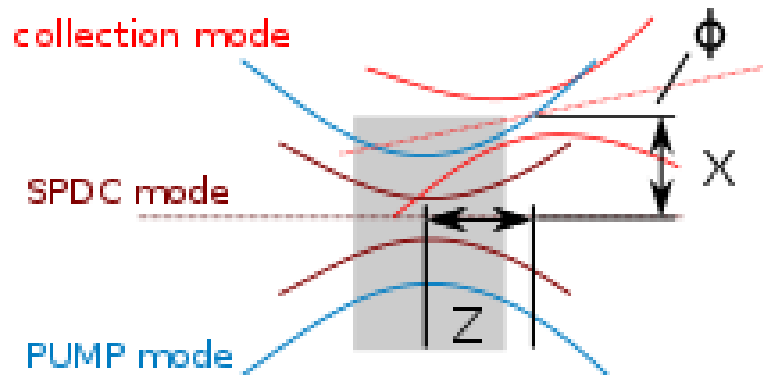
Specification	Goal
Total Mass	≤ 3 kg
Total Size	≤ 150 x 150 x 100 mm ³
Total Power Consumption	≤ 10 W (peak)
Visibility	> 98 % in 0°/90° and +45°/-45° basis
Detection rate*	0.64e6 photon pair events/s

* estimated for 25 mW pumping power

S. Ramelow, A. Mech, M. Giustina, S. Gröblacher, W. Wieczorek, J. Beyer, A. Lita, B. Calkins, T. Gerrits, S. Nam, A. Zeilinger, and R. Ursin, "Highly efficient heralding of entangled single photons," Opt. Express 21, 6707-6717 (2013).

Engineering Approach

Optical Design – Mechanical Tolerances



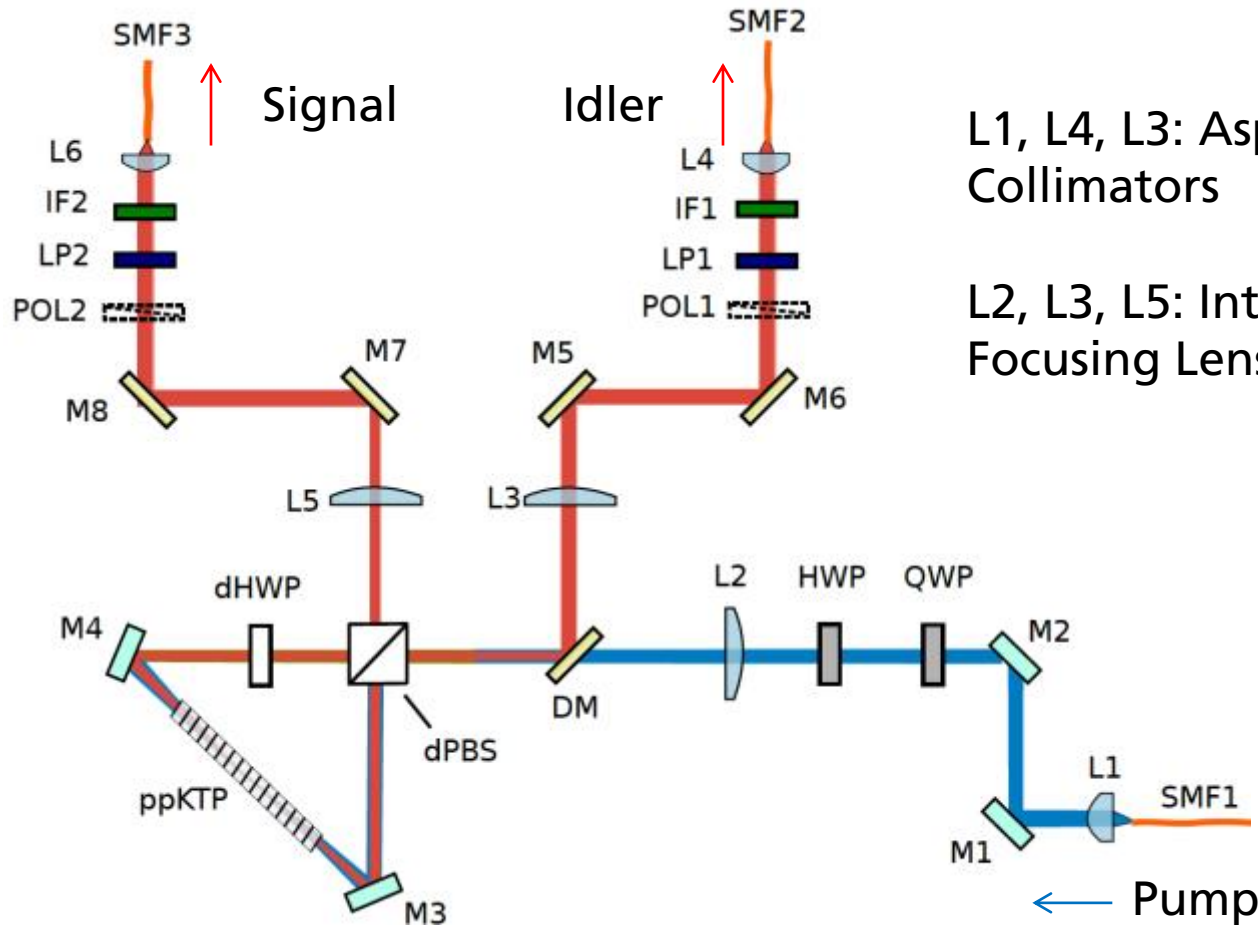
Definition of angular dealignment (ϕ), transverse dealignment (X), and axial dealignment (Z) of the collection mode with respect to the SPDC emission.

	Beam Parameters				Calc. Efficiency		Est. Exp. Rates		99% TOLERANCE			95% TOLERANCE		
	ζ_p	ζ_s	$w_p/\mu\text{m}$	$w_s/\mu\text{m}$	η	pairs/nm	rate	@ 20mW	$X/\mu\text{m}$	Z/mm	$\phi/\mu\text{rad}$	$X/\mu\text{m}$	Z/mm	$\phi/\mu\text{rad}$
Optimal Bragg	2,84	2,84	18	26	0,75	1,00	1,86	Mcps	2,6	1,0	490,0	5,9	2,5	1100,0
Trade-off 1	1,00	1,60	31	35	0,79	0,86	1,60	1 Mcps	3,5	1,9	364,0	7,9	4,4	823,0
Trade-off 2	0,55	1,20	42	40	0,85	0,70	1,30	Mcps	4,4	3,2	302,0	10,0	7,3	683,5
Trade-off 3	0,10	0,68	98	53	0,90	0,24	0,45	Mcps	5,3	4,4	240,0	12,0	10,1	544,0
Optimal Her	0,03	0,20	178	98	0,97	0,09	0,14	1 Mcps	10,0	15,8	127,0	22,6	36,0	288,0

- Trade-off 2: most sensible between heralding efficiency, pair-generation rate and transverse misalignment tolerance
- Expected: 1 million coincidences per mW for <15mW of pump power

Engineering Approach

Optical Design - Layout

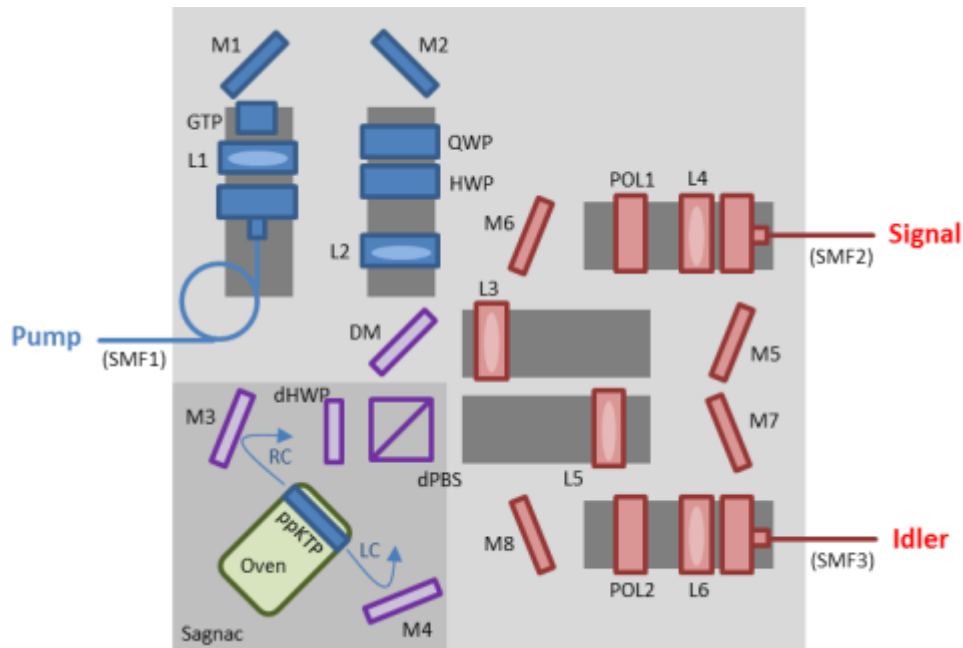


The Lab-Model of the EPS provides basic Parameters for the Design (Pathlengths, Distances, Alignment Tolerances) and thus is the major basis for the EQM Design!

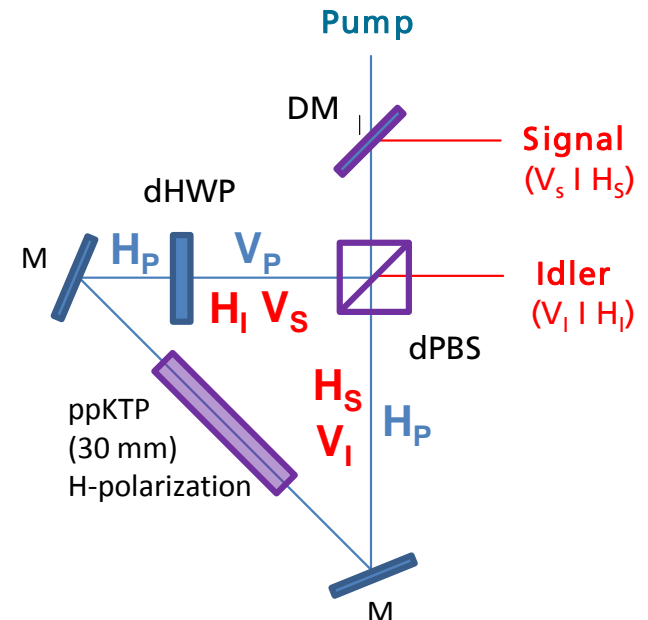
Engineering Approach

Lab Model – Setup Space-EPS

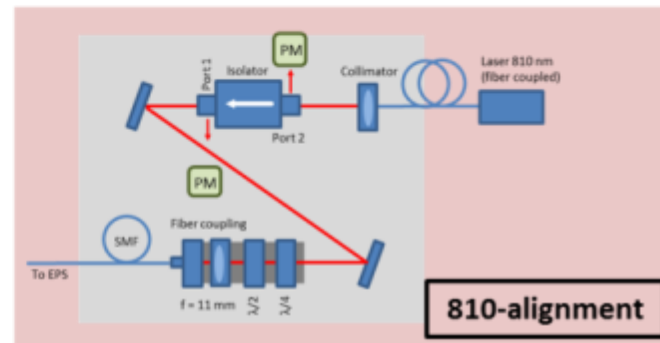
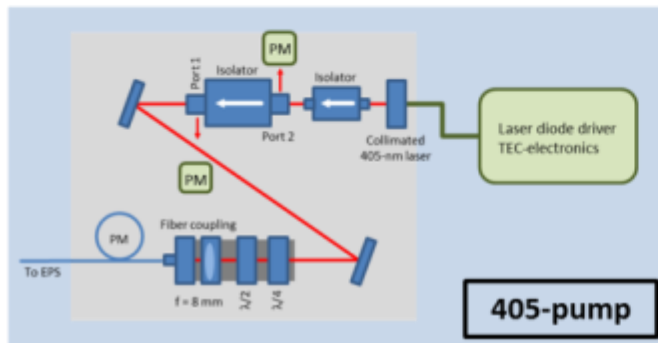
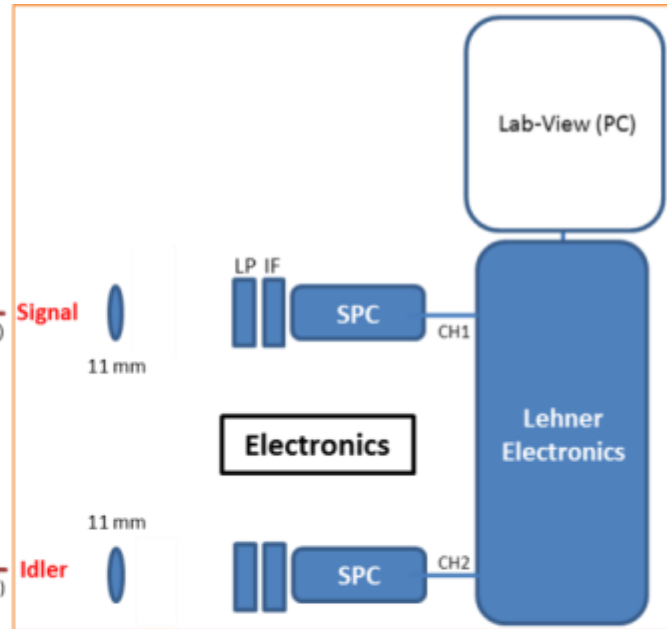
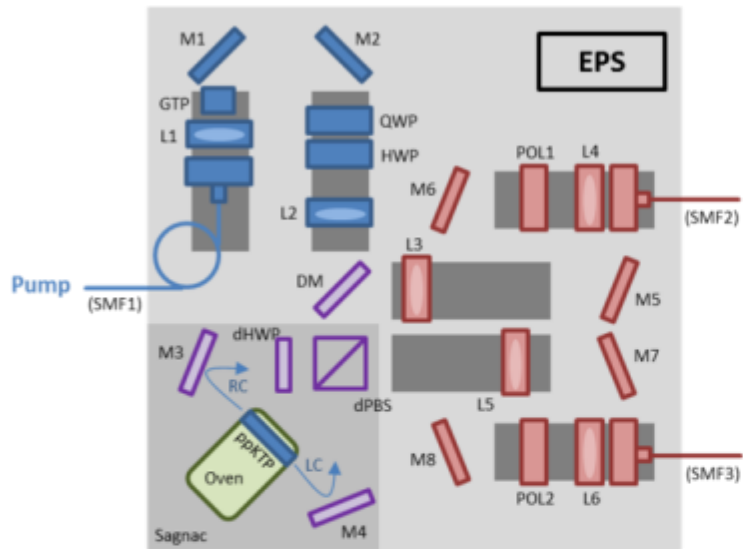
■ Setup of the Space-EPS Lab-Model



Sagnac interferometer

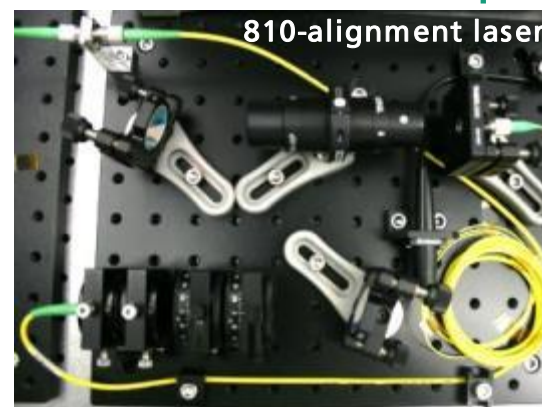
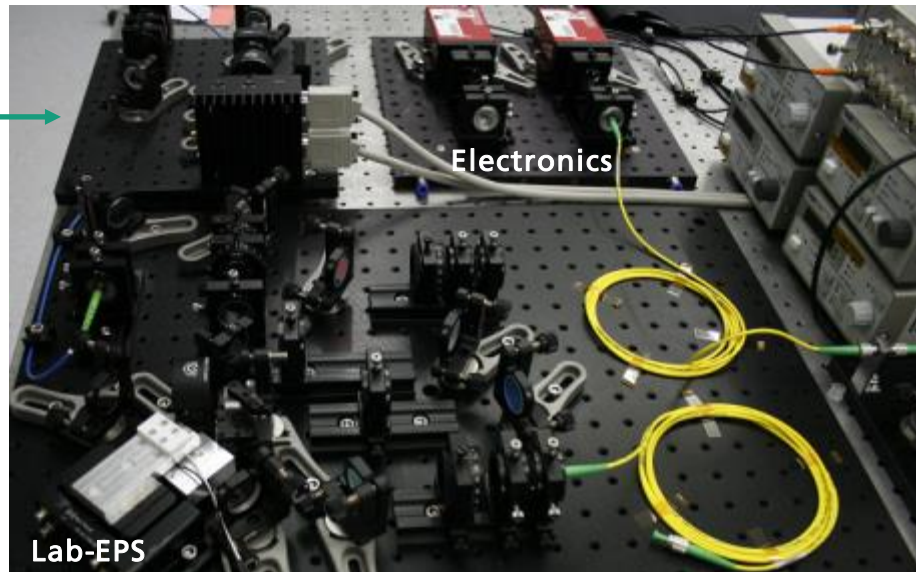


Lab Model – Setup Space-EPS & External Devices



Engineering Approach

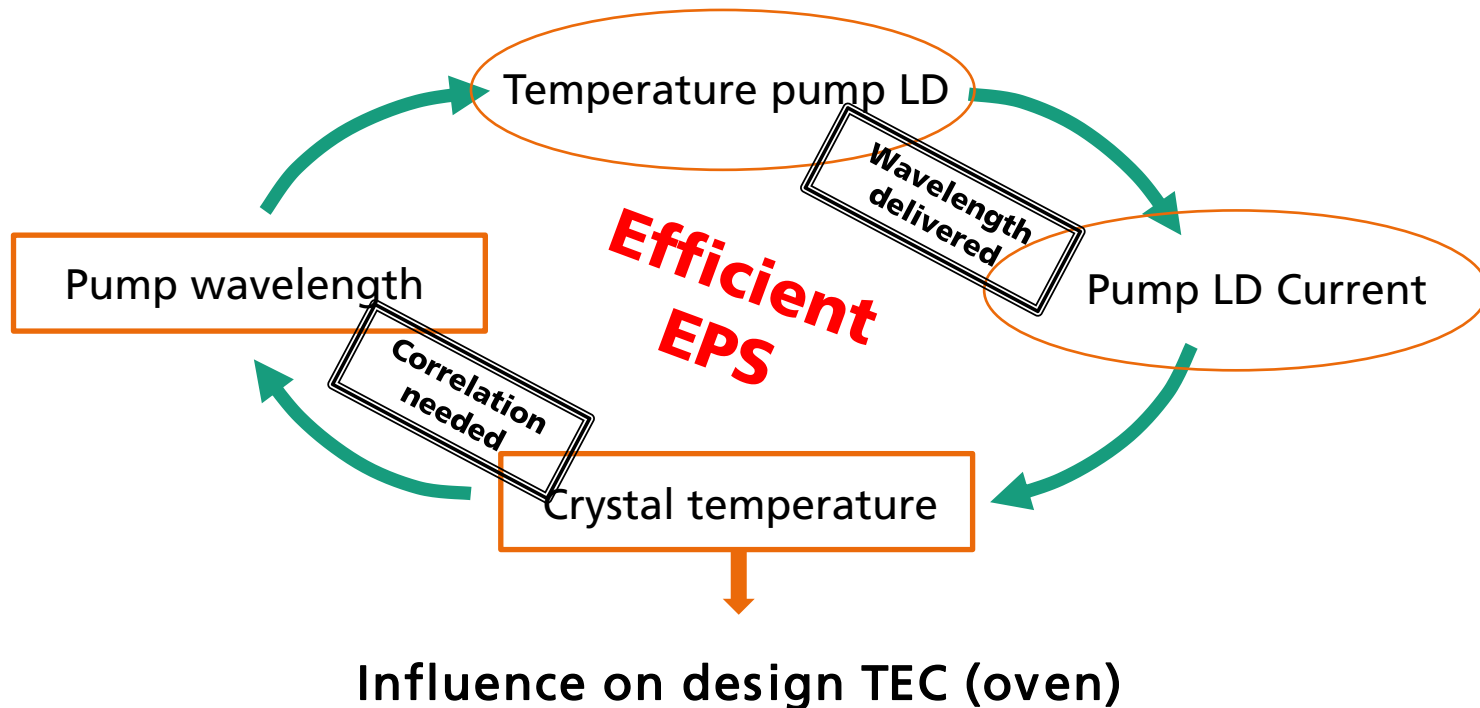
Lab Model – Realized Setup



Engineering Approach

Lab Model – Crystal Temperature vs. Pump Wavelength

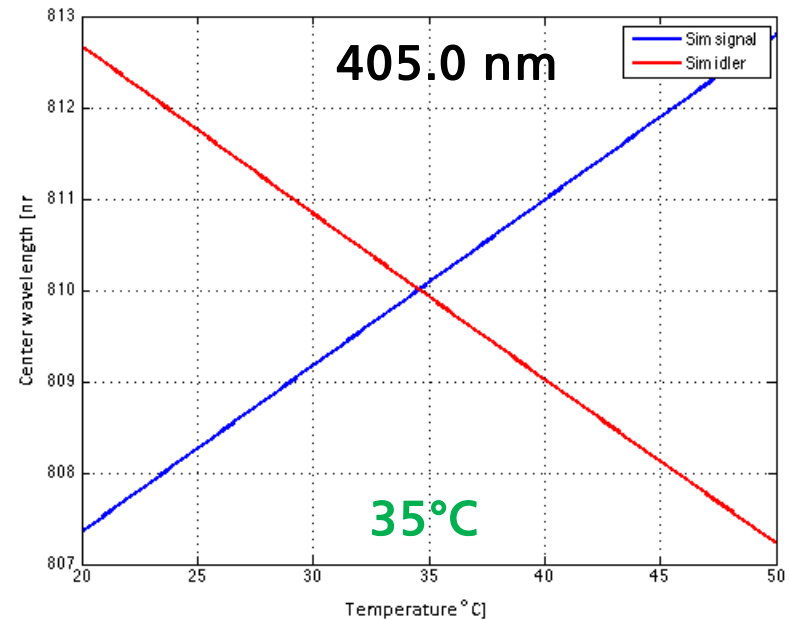
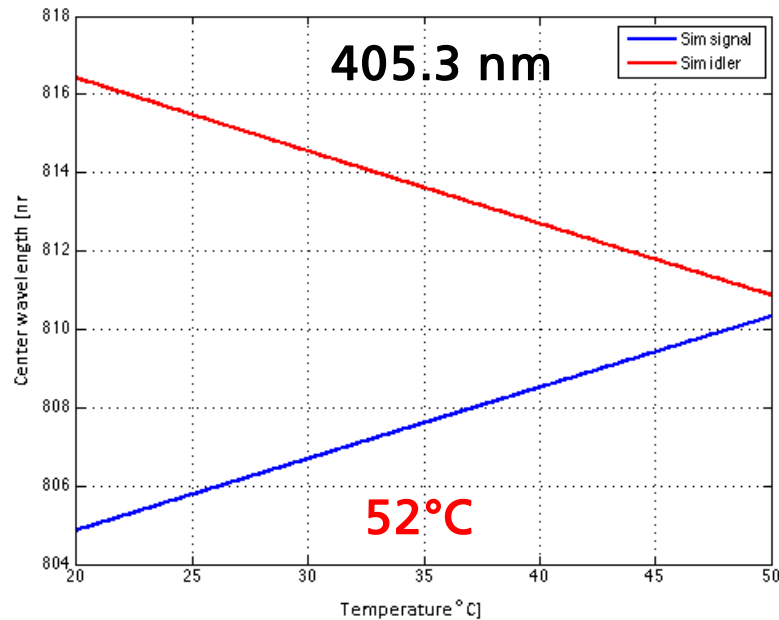
■ Catch-22 situation:



Engineering Approach

Lab Model – Crystal Temperature vs. Pump Wavelength

- Correlation pump wavelength / crystal temperature:

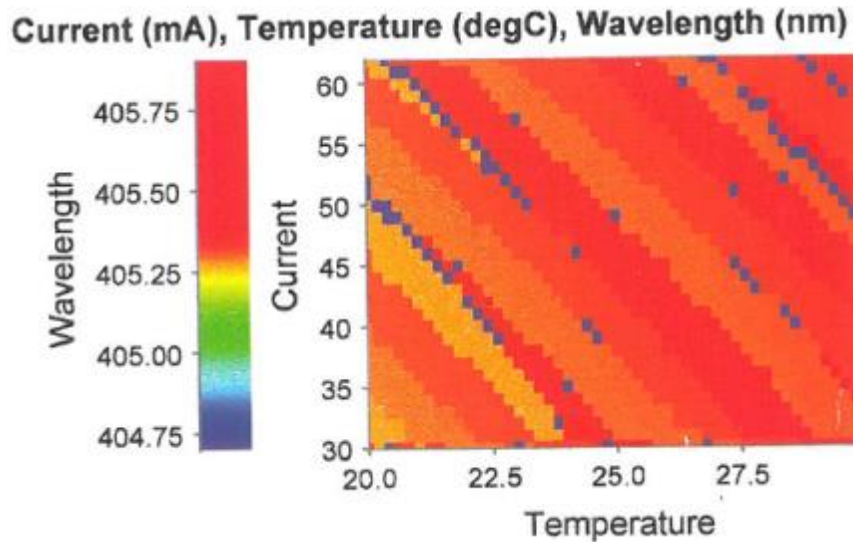


→ Small changes on pump wavelength have huge impact !

Engineering Approach

Lab Model – Crystal Temperature vs. Pump Wavelength

- Wavelength delivered by ONDAX-LDs used:



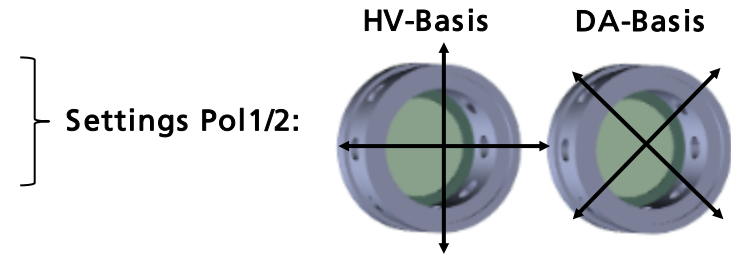
- Only one of three ordered diodes provide 405.0 nm at all
- Usable power only $P = 4.6$ mW (due to: non-polarized, not fiber coupled LD)
- Desired Pump-LD: locked wavelength @ locked current / temperature

Engineering Approach

Lab Model – Results

■ Results from Lab-EPS @ full available pump power (4.6 mW, $T_{\text{oven}}=36^{\circ}\text{C}$):

- HV-visibility: $V_{H/V} = \frac{n_{H/V} + n_{V/H} - n_{H/H} - n_{V/V}}{\sum n_{ij}}$
- DA-visibility: $V_{D/A} = \frac{n_{D/A} + n_{A/D} - n_{D/D} - n_{A/A}}{\sum n_{ij}}$



V_DA [%] =	96,9837	Error V_DA [%] =	0,0155
V_HV [%] =	99,0565	Error V_HV [%] =	0,0084
Power (in EPS) /mW:	4,60		
Pair-Counts (over 60s):	18992277		
Pair-Counts (per second) =	316538		
Laser diode current /mA:	55,000		
Laser diode NTC /kOhm:	11,000		
Crystal oven NTC /kOhm:	6,265		

Goal parameters:

- Count-Rate $> 100.000 \text{ s}^{-1}$
- Visibility HV-Basis $\geq 98 \%$
- Visibility DA-Basis $\geq 98 \%$

Engineering Approach

Lab Model – Results

- But with “special excited” pump mode and without realigning EPS ...

V_DA [%] =	98,1971	Error V_DA [%] =	0,0304
V_HV [%] =	98,9941	Error V_HV [%] =	0,0224
Pair-Counts (over 60s @1mW):		2804996	
Pair-Counts (@ 1mW/s) =		46750	

Goal parameters:

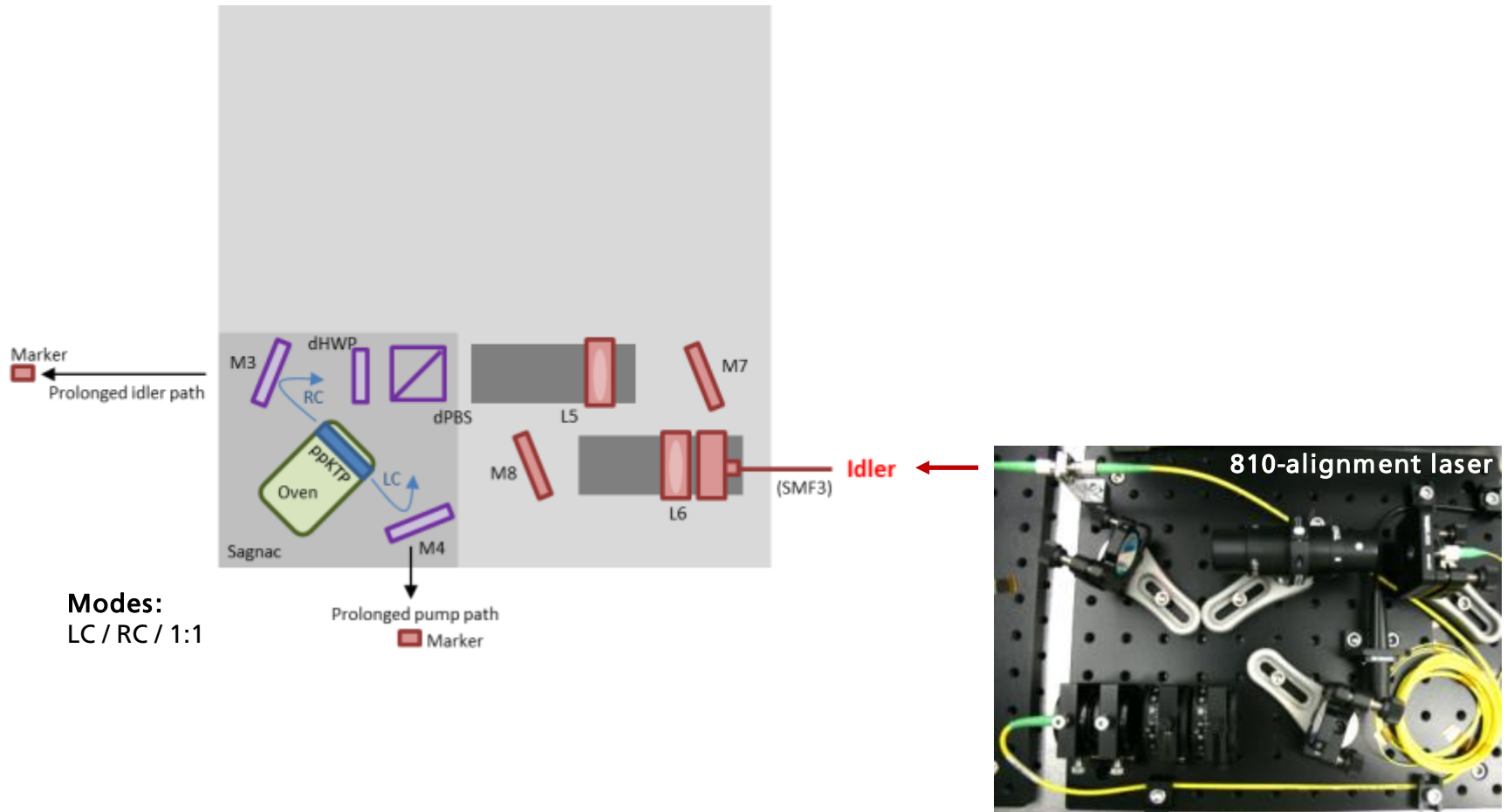
→ Visibility DA > 98 %

- ... also >98% DA-visibility can be reached (but is difficult to control) !
 - Current results prove a predominant influence of the (external) pump laser diode over alignment issues
 - No “better” pump diode available at the moment
 - But: DA-visibility may improve using Glan-Thompson polarizer in the pump path (PER 100.000:1) !

Engineering Approach

Lab Model - Assembly Algorithm Derivation

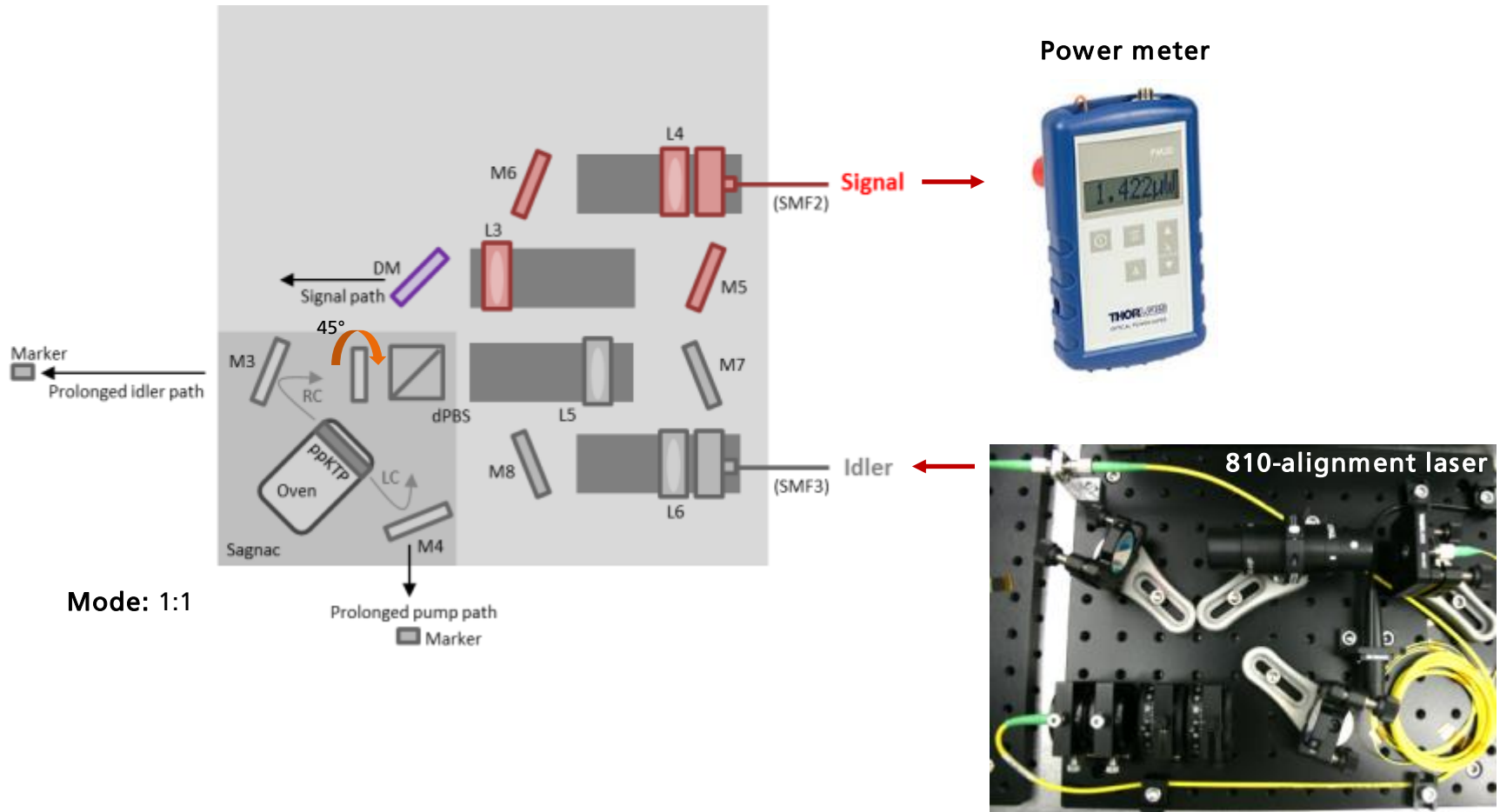
■ Alignment algorithm: Step 1 („Reference path“)



Engineering Approach

Lab Model - Assembly Algorithm Derivation

■ Alignment algorithm: Step 2 („Signal path“)

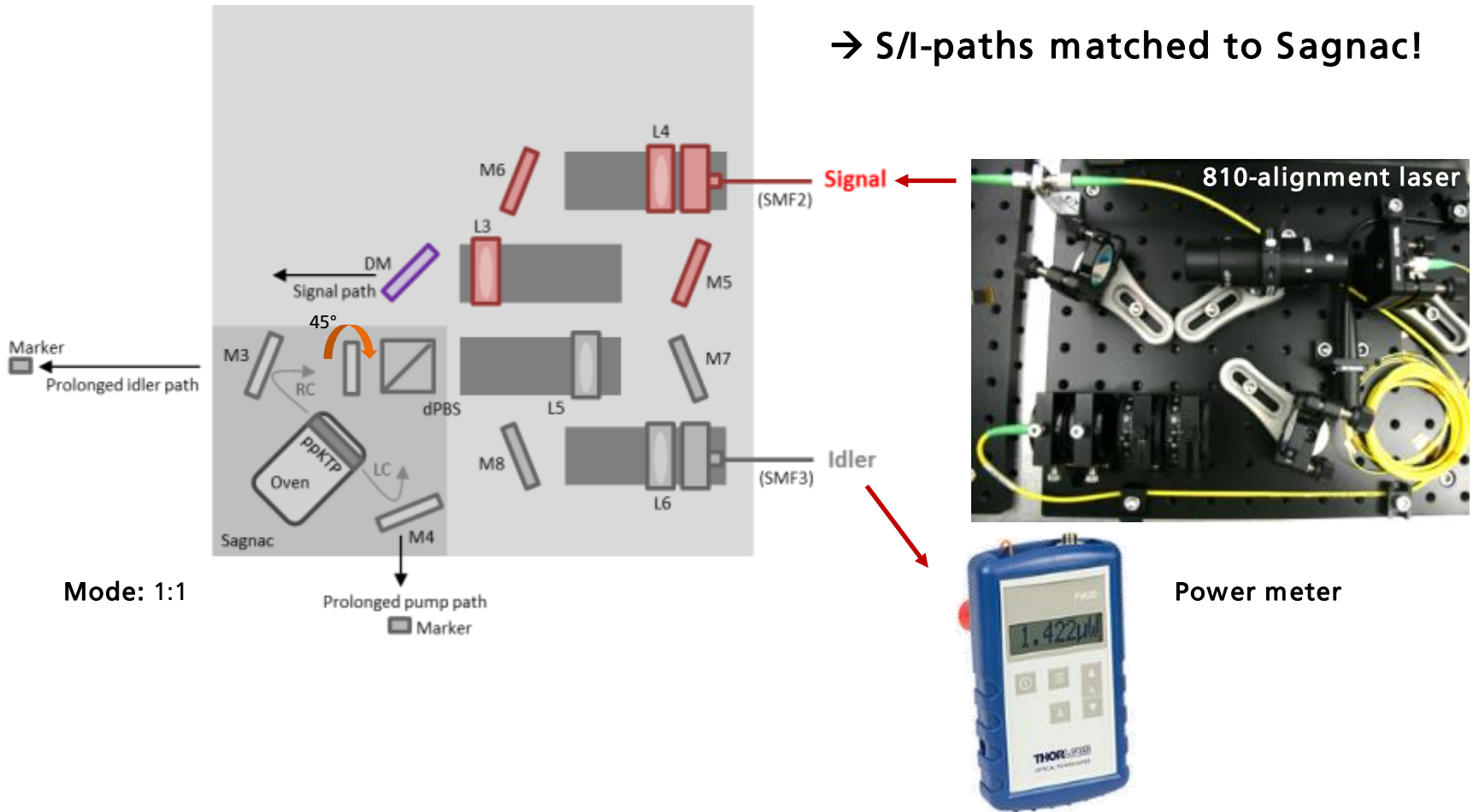


Engineering Approach

Lab Model - Assembly Algorithm Derivation

- Alignment algorithm: Step 3 („Check symmetry“)

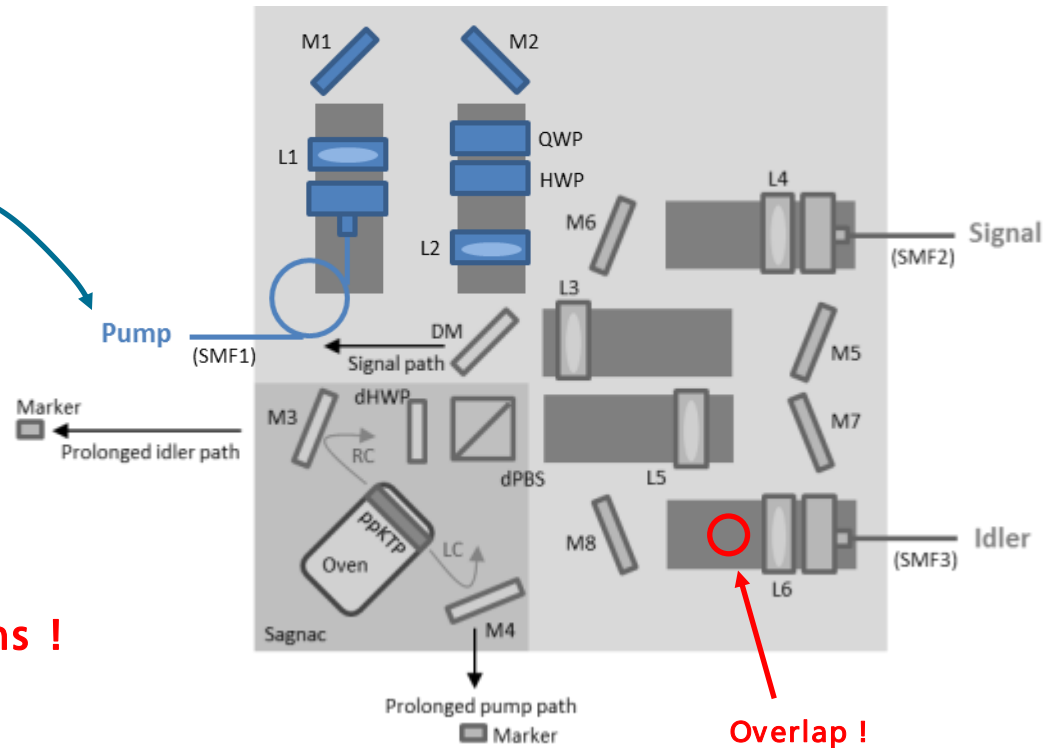
→ S/I-paths matched to Sagnac!



Engineering Approach

Lab Model - Assembly Algorithm Derivation

■ Alignment algorithm: Step 4 („Pump path“)

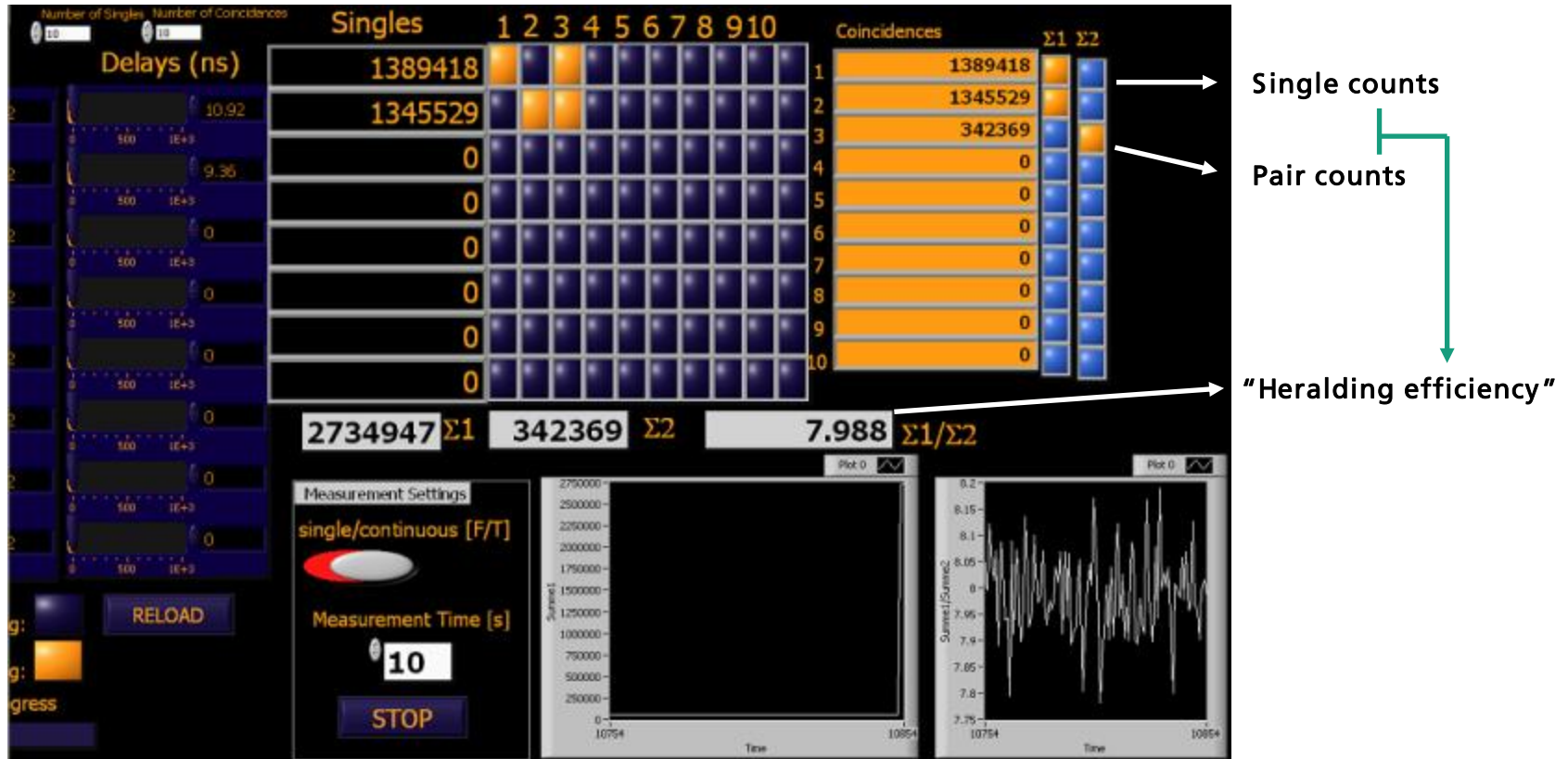


→ P-path matched to S/I-paths !

Engineering Approach

Lab Model - Assembly Algorithm Derivation

- Start Quantum-level alignment via LabView:



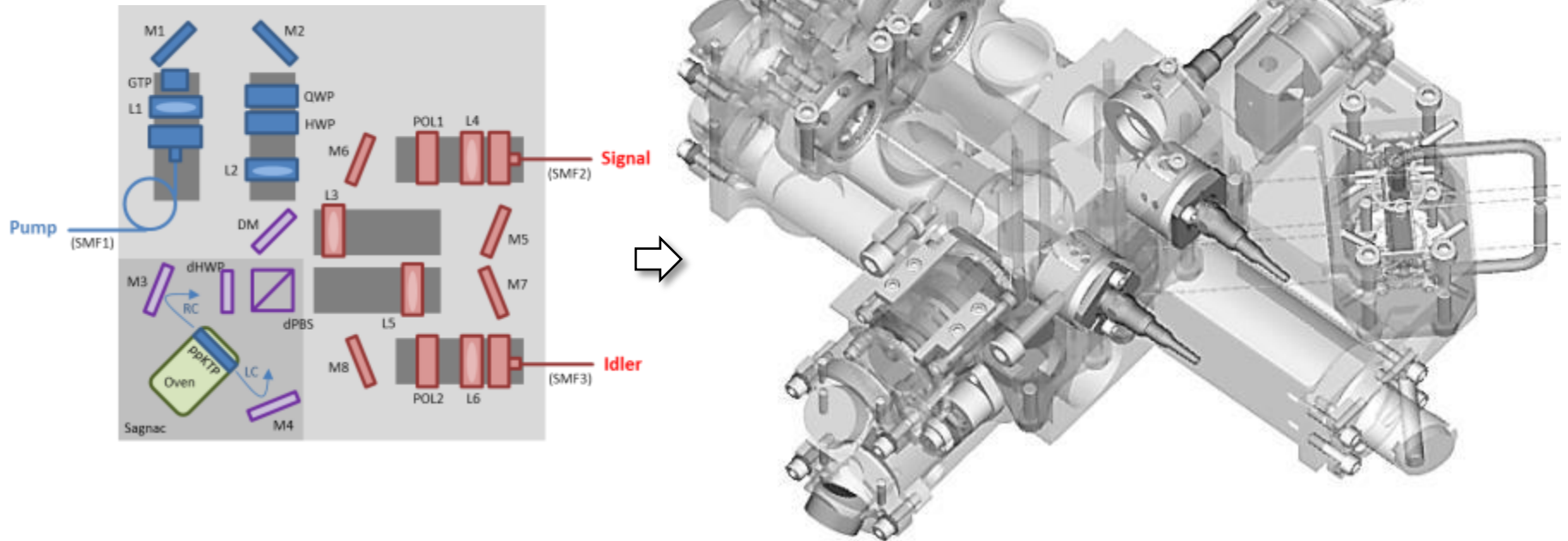
Engineering Approach

Lab Model – Derivation of Assembly DOF, Precision

Component	Material	Aperture	DOF (initial positioning)	DOF (SPDC/LD alignment)	DOF (operation)	Resolution	T dependence
Optical EPS components							
SMF1	silica	NA=0.12	Dv,Dh,Dz	-	-	high	low
SMF2	silica	NA=0.12	Dv,Dh,Dz	-	-	high	high
SMF3	silica	NA=0.12	Dv,Dh,Dz	-	-	high	high
M1,M2	fused silica	12.5mm	Rv,Rh	Rv,Rh	-	high	?
M3,M4	fs substrate	12.5mm	Rv,Rh	Rv,Rh	-	high	?
M5-M8	?	12.5mm	Rv,Rh	Rv,Rh	-	high	?
L1	model-depende	9mm	Dv,Dh,Dz	-	-	med	?
L2	fused silica	12.5mm	Dv,Dh,Dz	Dz	-	low	?
L3	BK7	12.5mm	Dv,Dh,Dz	Dz	-	low	?
L5	BK7	12.5mm	Dv,Dh,Dz	Dz	-	low	?
L6,L4	model-depende	9mm	Dv,Dh,Dz	Dz	-	med	?
dHWP	quartz	12.5mm	Rv,Rh,Rz	Rz	-	low	high
dPBS	BK7/FS	10mm	Rv,Rh	-	-	low	?
DM	FS	custom	Rv,Rh	Rv,Rh	-	med	?
HWP	quartz	10mm	Rv,Rh	Rz	Rz	0.5°	low
QWP	quartz	10mm	Rv,Rh	Rz	Rz	0.5°	low
PPKTP	KTP	1x2mm2	Rv,Rh,Dv,Dh,Dz	Rv,Rh,Dz	-	med	high
IF1,IF2	?	12.5mm	Rv,Rh,Dv,Dh,Dz	-	-	low	?
LP1,LP2	?	12.5mm	Rv,Rh,Dv,Dh,Dz	-	-	low	?
POL1,POL2	?	12.5mm	Rv,Rh,Dv,Dh,Dz	Rz	Rz	0.5°	low

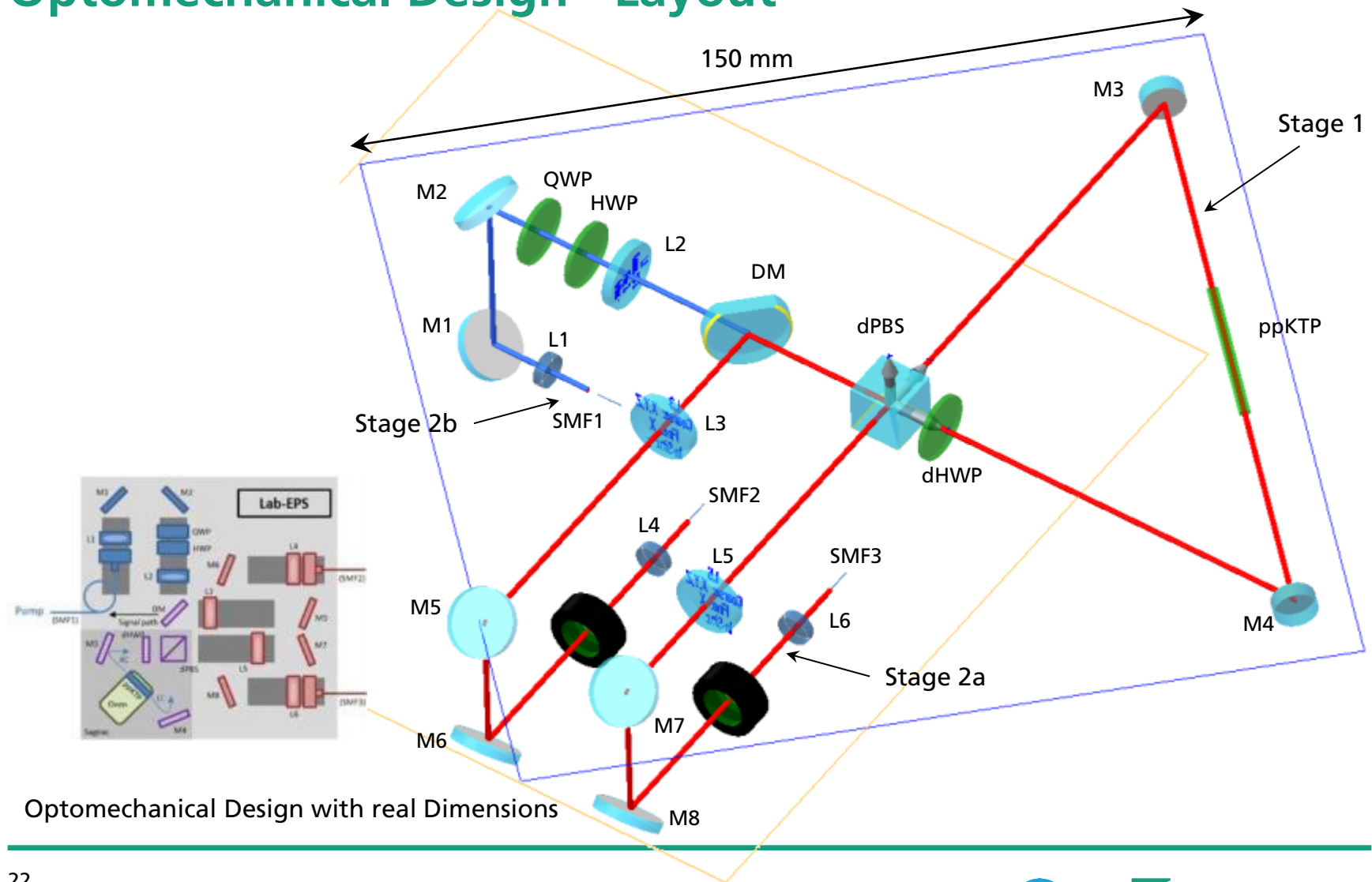
Engineering Approach

From the Lab Model to the EQM



Engineering Approach

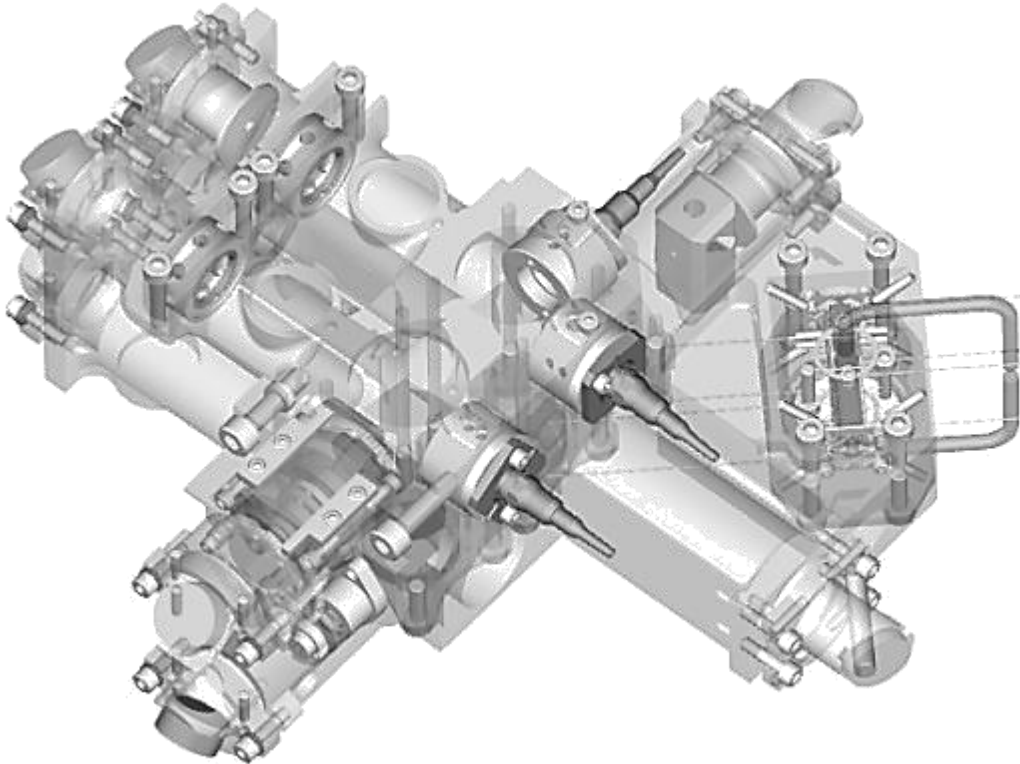
Optomechanical Design - Layout



Optomechanical Design with real Dimensions

Engineering Approach

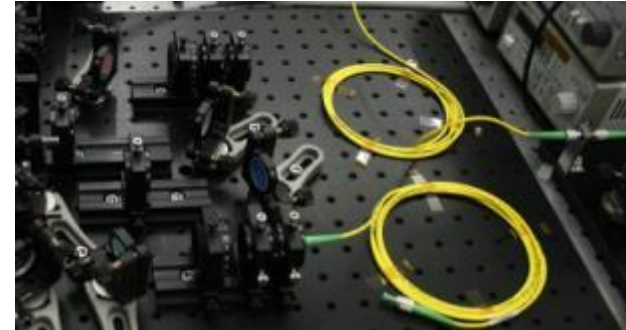
Optomechanical Design - Principles



- INVAR „lightweight“ base structure
- Precision stops and guidings for alignment, e.g. alignment turned lenses
- Anorganic, robust bonding of components - soldering

Engineering Approach

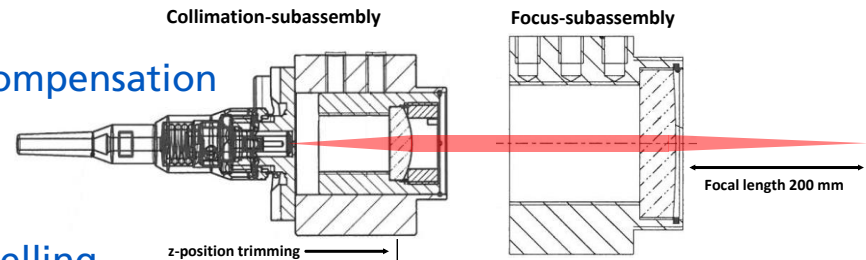
EQM Design Details



○ Lab-Model

○ The transition into Engineering Model

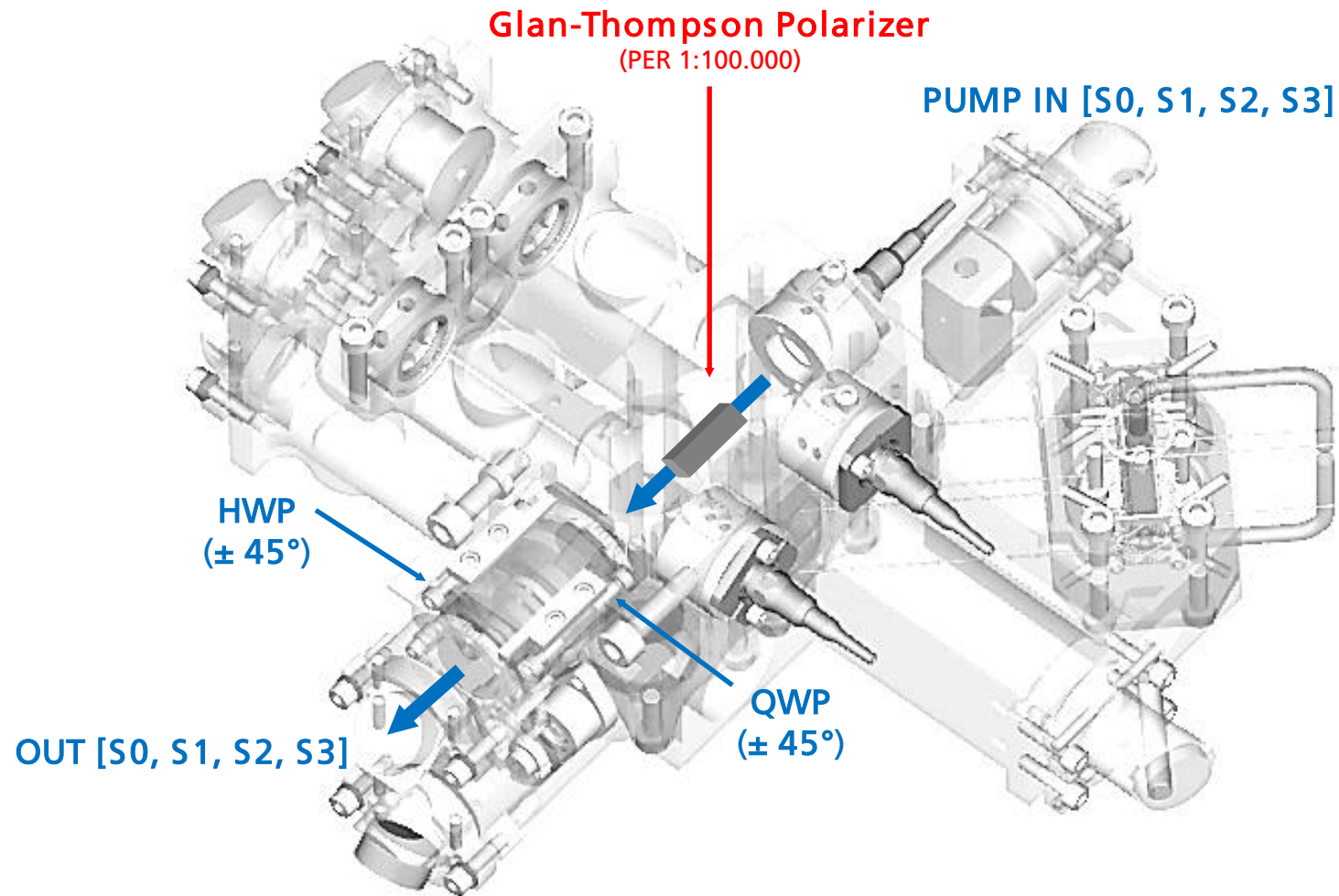
- Glan-Thompson integration
- Pump beam displacement compensation
- Trimming procedure
- lens combinations
- ppKTP temperature levelling
- Component manufacturing
- Sub-assembly preparation



○ GOAL: EQM-prototype for testing

Engineering Approach

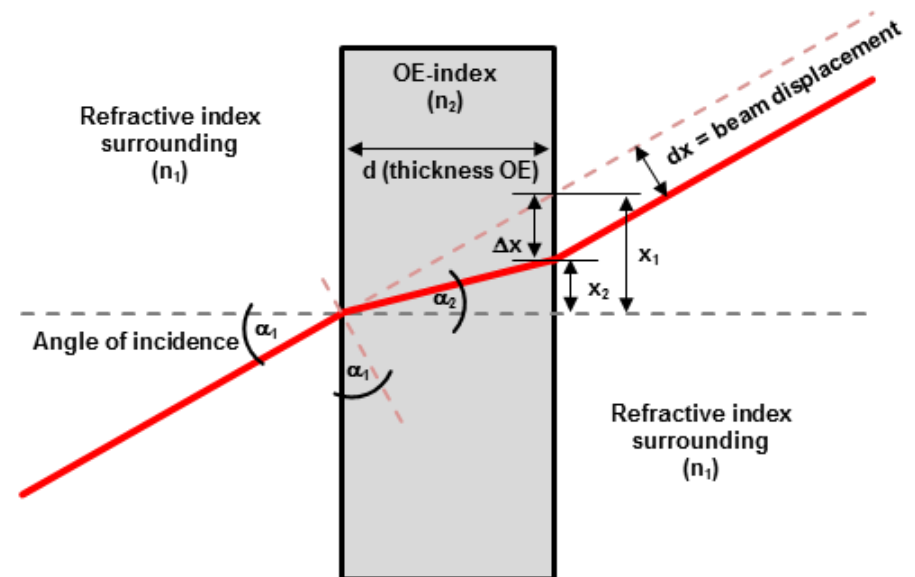
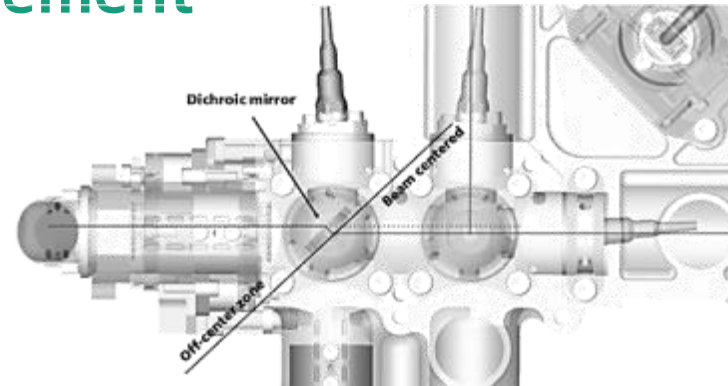
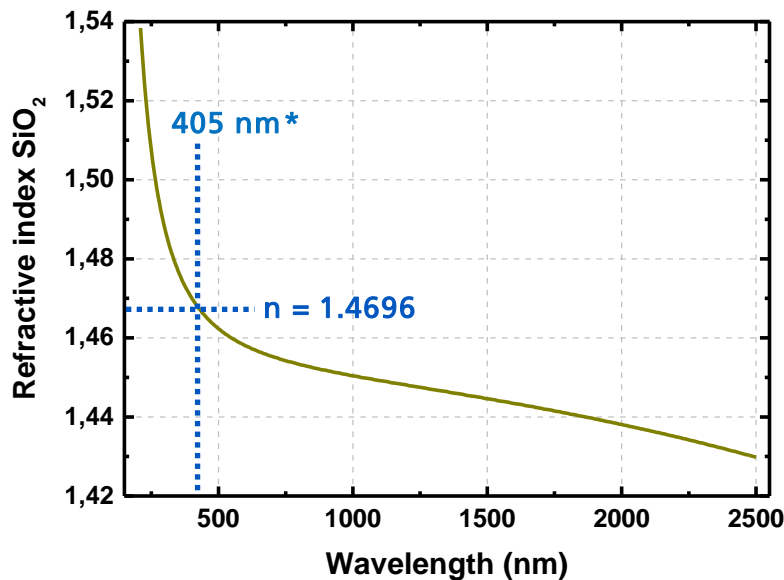
Design Details – Pump Polarization



Engineering Approach

Design Details – Beam Displacement

■ Compensating beam displacement

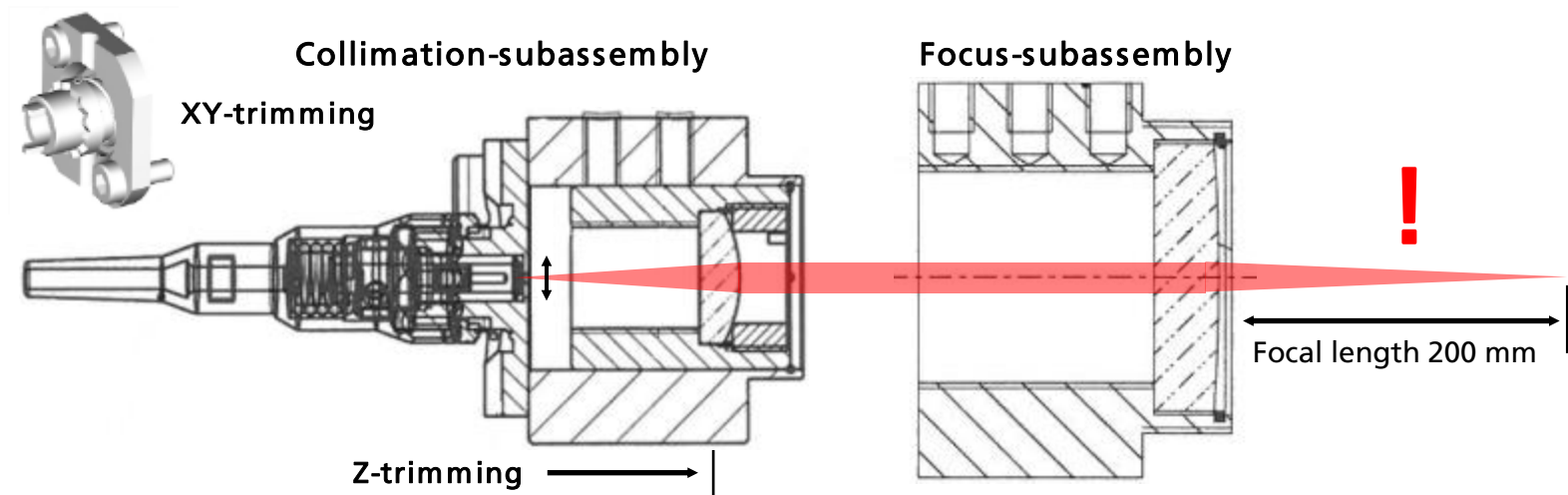


→ Beam displacement 638 μm (off-center propagation pump-path)

Engineering Approach

Design Details – Collimator / Focus Trimming

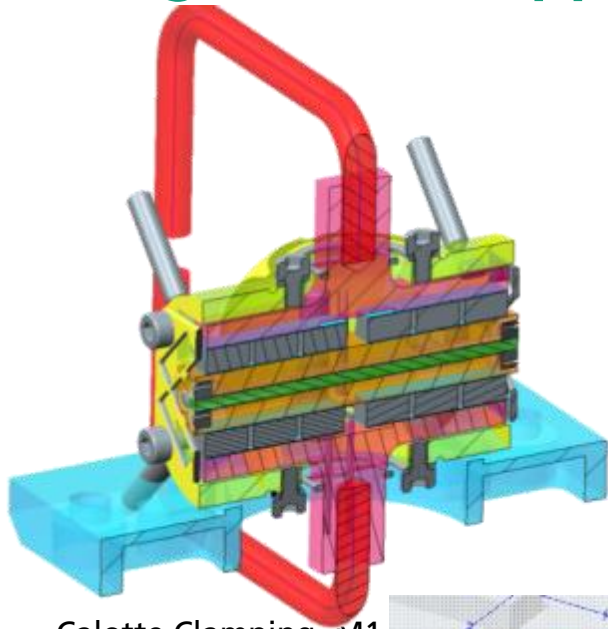
- Trimming procedure of collimating / focussing lens pair
 - Basic scheme for matching lens pair:



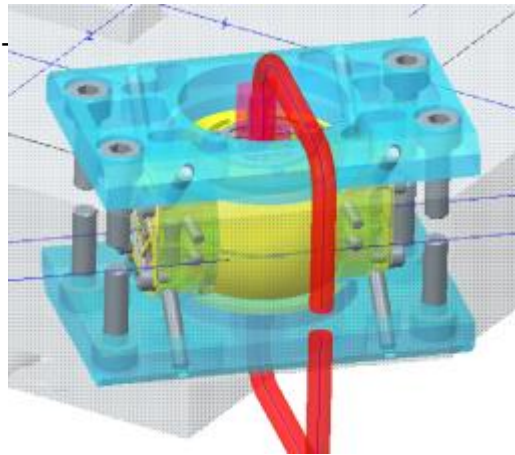
- Centering of fiber-tip (XY-adjustment mounting plate)
- Trimming of z-position of collimating lens
- Once trimmed and assigned, no later adjustment needed !

Engineering Approach

Design Details – ppKTP Temperature Levelling



Calotte Clamping, M1-

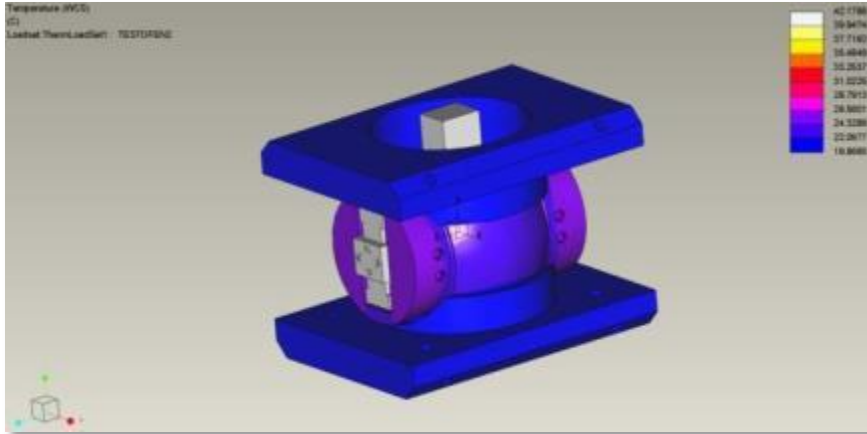


„Oven“ Integrated
in Platform

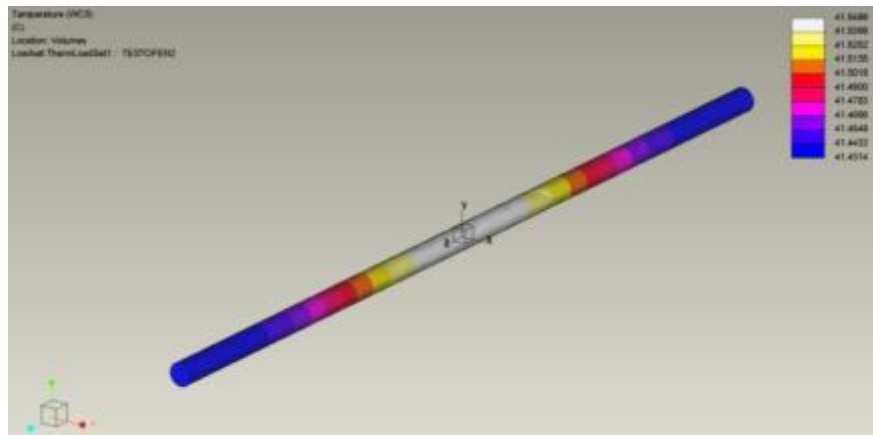
- Fully symmetric, temperature Distribution optimized Assembly
- Cu-Mount and DC93-500 heat conducting Silicone for ppKTP; Peltier Elements for Heat Pumping
- TiAl6V4 Flexures for mechanical decoupling
- INVAR Calotte for Tip/Tilt Alignment of Crystal

Engineering Approach

Design Details – ppKTP Temperature Levelling



Calotte Model



Temperature-Distribution within central Region of Crystal

- Goal: Even Temperature Distribution with ca. 0.1K in Pump Region of ppKTP
- Set Temperature within Crystal: ca. 41°C
- Environment: 20°C
- Heat Load within Crystal: ca. 10mW (worst case)
- Result of Optimization: ΔT within Crystal ca. 0.11K

Engineering Approach

Design Verification Matrix

Level	Description	Goal	Condition	Status CDR
Mechanical System Parameters				
System	Overall weight	$\leq 1.5 \text{ kg}$	Calculated by design	3 kg without lightweight structured platform
System	Overall dimensions	$\leq 100 \times 100 \times 80 \text{ mm}^3$	Calculated by design	$150 \times 150 \text{ mm}^2$ <80 mm height
System	Mechanical stability	Tbd: load vs. optical tolerances	Calculated by FEA	n.a.
Electrical System Parameters				
System	Overall power consumption	<8 W	Estimated by analysis	Crystal Temperature: max. 0.2 W (@ ΔT 20K)
Thermal System Parameters				
System	ppKTP temperature stability	<0.5 K	Calculated by FEA	0.11 K

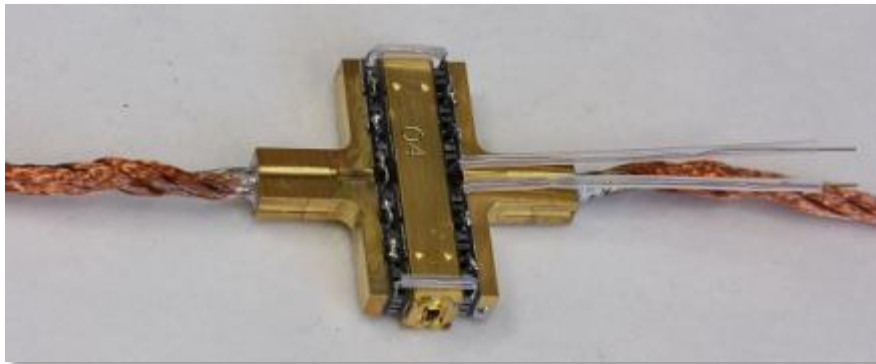
Current Status

EQM Components – ppKTP Temperature Leveller



Electroplated Calotte half Spheres

- INVAR Calotte
- Electroplated Ni/Pd/Au
 - Defined Thickness 5..10 μm
 - NiP 7,5 μm ±20%
 - Pd 0,3 μm ±30%
 - Au 0,01 μm - 0,06 μm



Heat Sink / Peltiers / Heatsink Sub-Assembly

- Cu Heatsink
- Sputtered Ti/Pt/Au (0,5 μm)
- Oven Soldering Crystal Heatsink/
Peltiers / Outer Heatsink



Current Status

EQM Components – ppKTP Temperature Leveller



Integrated Heatsinks and Peltiers and Springs

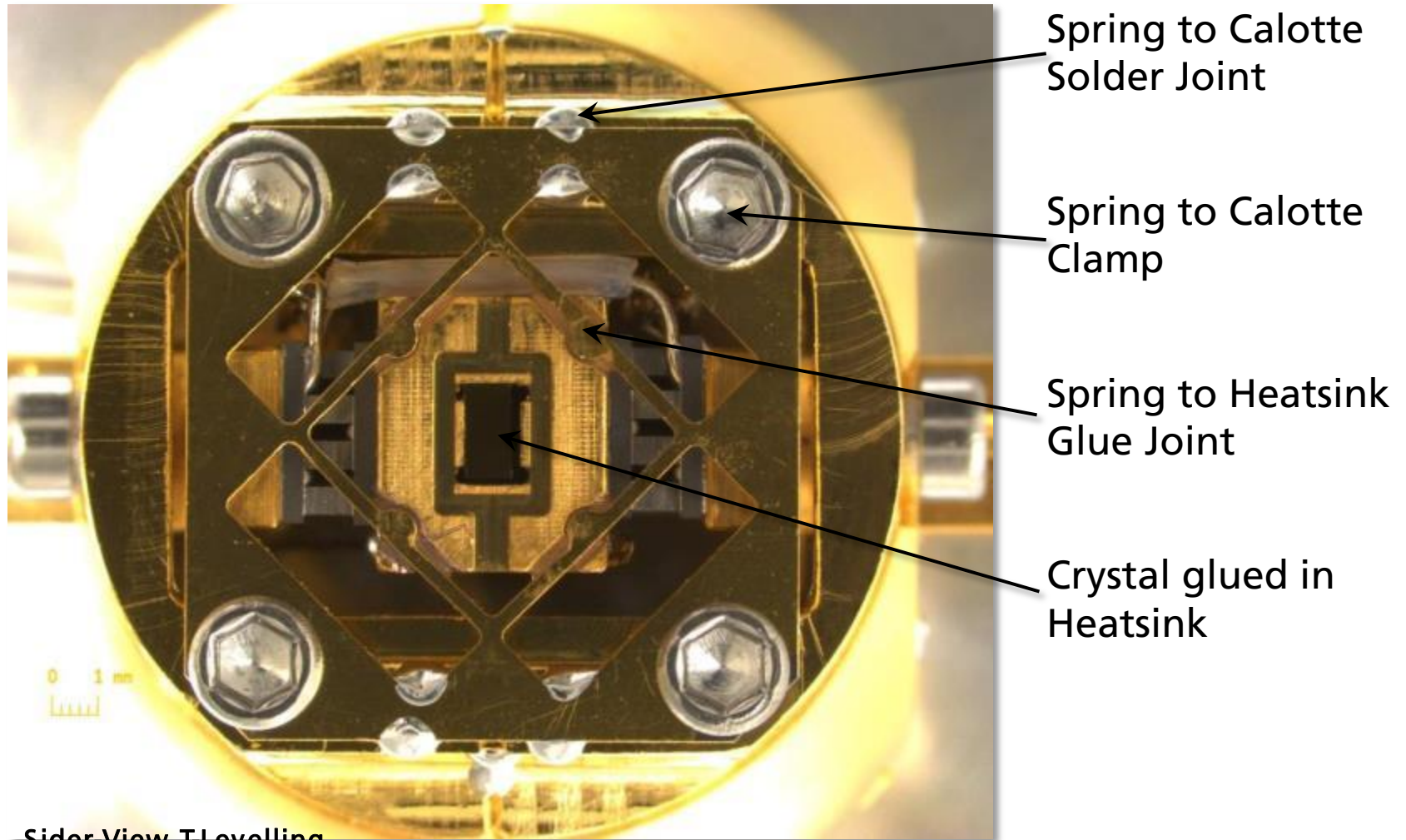


Integrated Calotte

- ppKTP Crystal glueing in Heatsink
- Spring Assembly by combining Clamping, Glueing and Soldering
- Calotte Assembly by Clamping and Soldering

Current Status

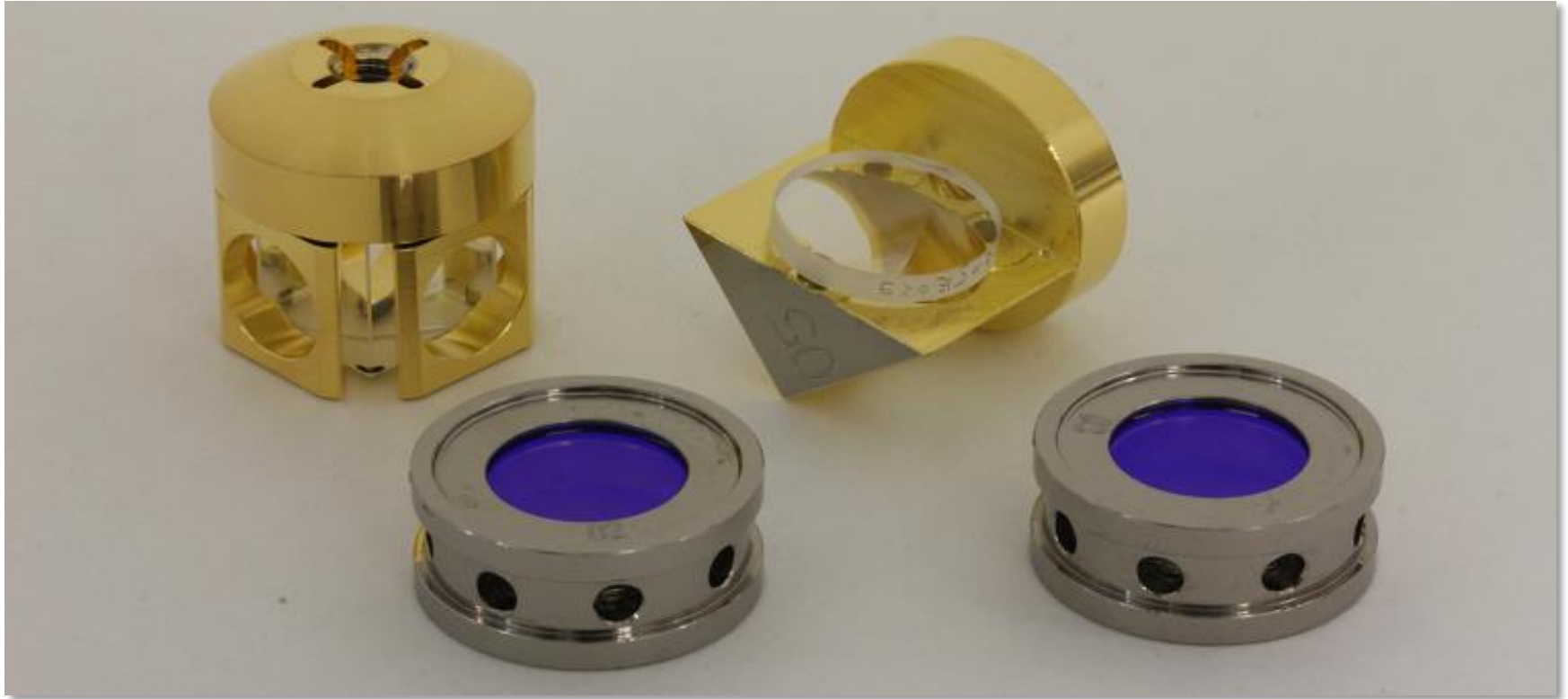
EQM Components – ppKTP Temperature Leveller



Sider-View T-Levelling

Current Status

EQM Components – passive Components



dPBS (upper left), DM (upper right), Analyzer and Polarizer (lower)

Current Status

EQM Components – Trimmed Fiber Collimators



Fully integrated Collimator Assembly



Backside View – Diamond Mini-AVIM Plug, soldered

Current Status

EQM Components – INVAR Base

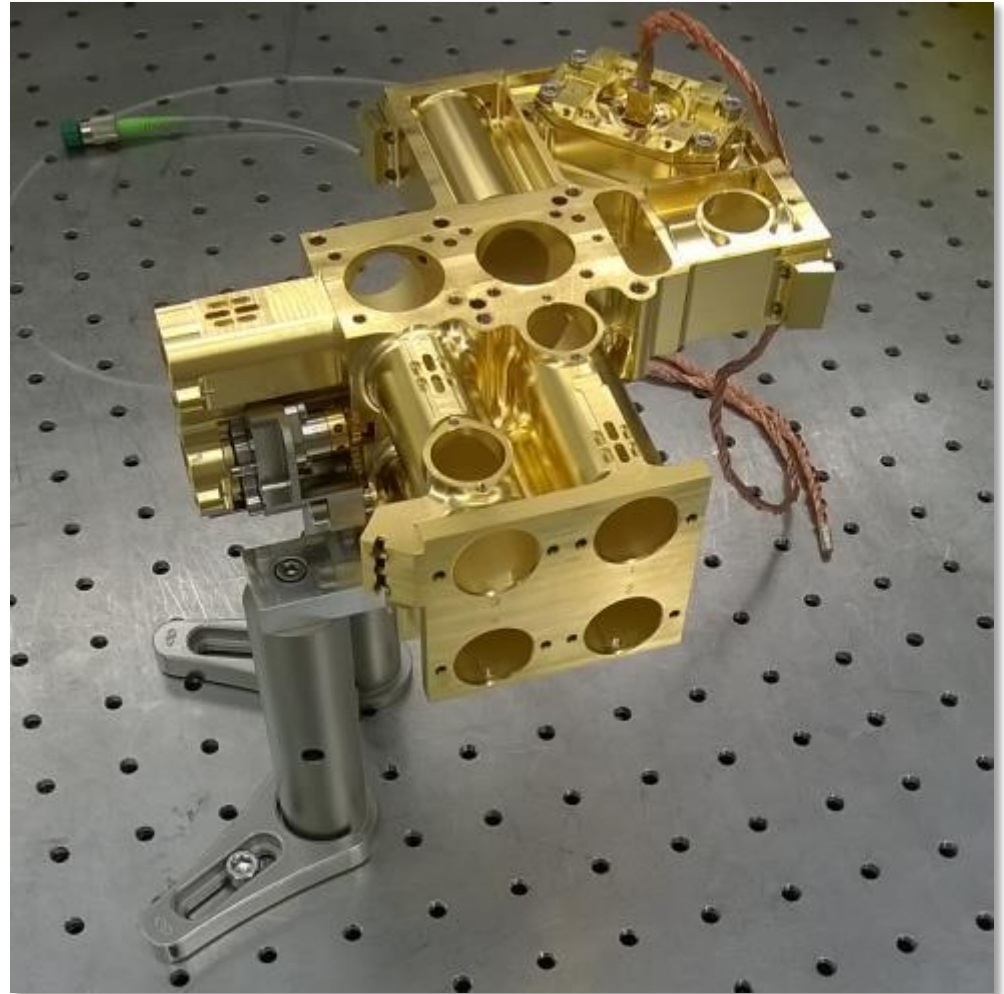
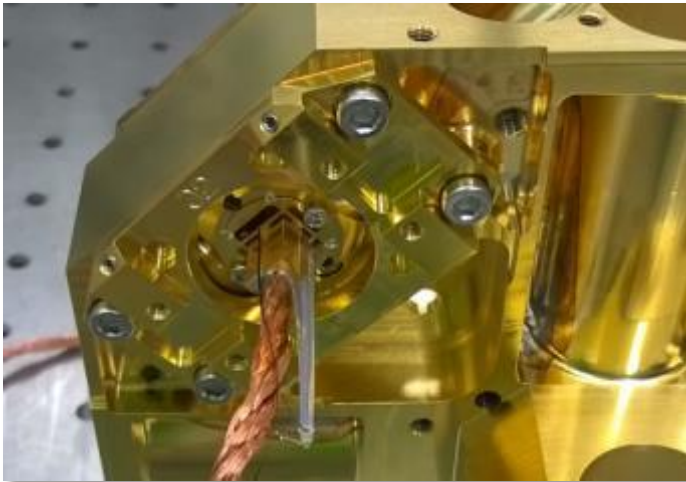


- INVAR Housing
- Electroplated Ni/Pd/Au
- Defined Thickness 5..10 μm
 - NiP 7,5 μm ±20%
 - Pd 0,3 μm ±30%
 - Au 0,01 μm - 0,06 μm



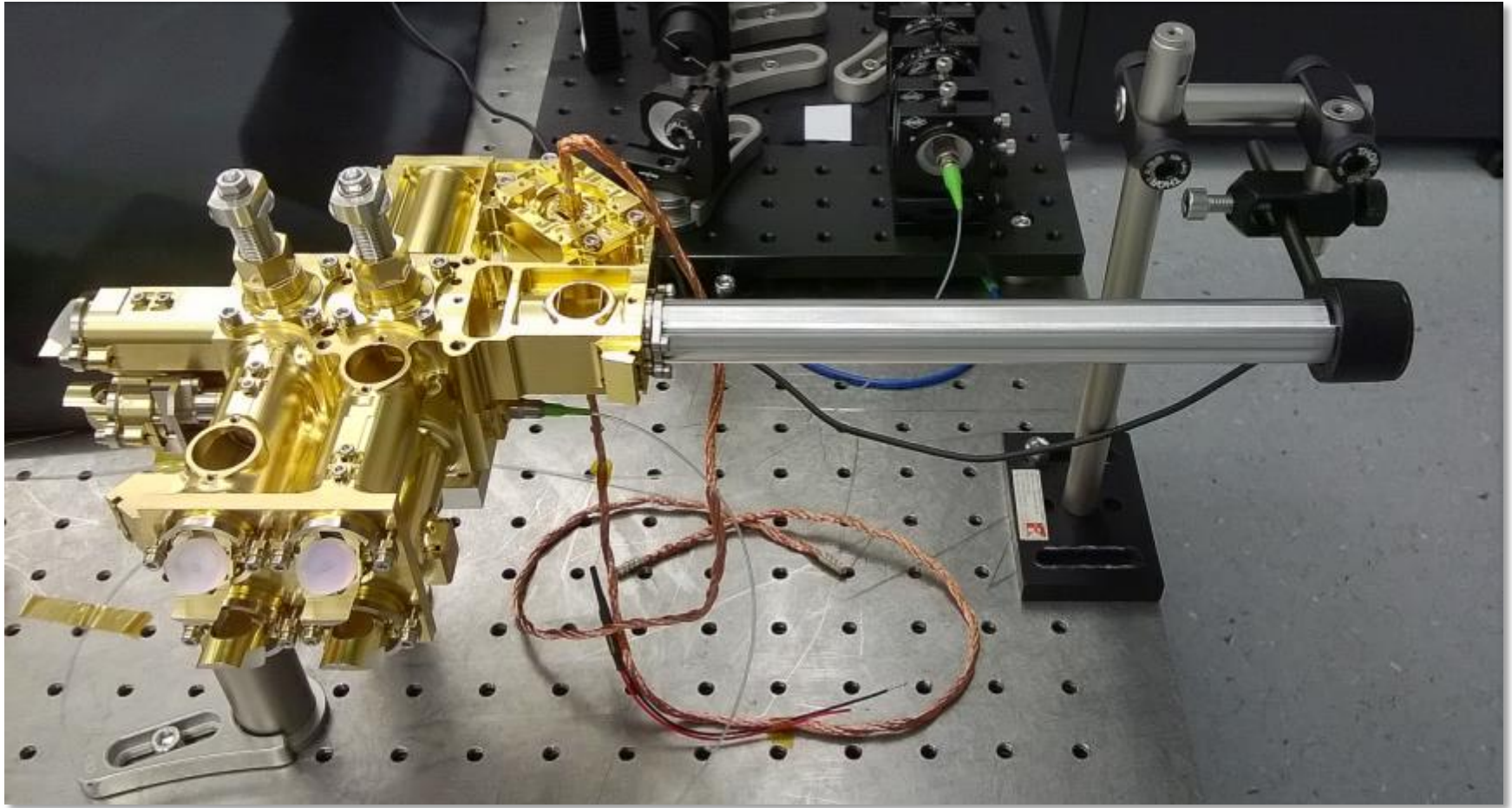
Current Status

EQM Assembly – 8th of December 2016



Current Status

EQM Assembly – 21st of March 2017



Outlook

EQM Evaluation – Test Plan

Task	Description	Measure
1	Initial Entanglement Quality	Visibility HV-Basis: n.n. % Visibility DA-Basis: n.n. % Pair Counts: n.n. / 60 s @ n.n. mW (measured) Pair Counts: n.n. / s @ 20 mW (calculated)
2	Non-Operational Temperature Cycling Test at normal Pressure	-40/+60 °C for 10 cycles, 2 °/min ramps
3	Post 1 st Test Entanglement Quality	See Task 1
4	Non-Operational Temperature Cycling Test at Vacuum	-40/+60 °C for 4 cycles, 2 °/min ramps, at 10 ⁻⁴ mbar
5	Post 2 nd Test Entanglement Quality	See Task 1
6	Mechanical Load Test	Acceleration 7.5 g, duration 3 min Sinusoidal vibration (resonance search range 5-2000 Hz at 0.5 g and 2 octaves/min, then sweep in in a range 5-21 Hz @ 11 g / 21-60 Hz @ 20 g / 60-100 Hz @ 6 g, each with 2 octaves/min and Random Vibration (resonance search range 5-2000 Hz at 0.5 g and 2 octaves/min), then all axes at 2.5 min/axis: 20-100 Hz (+3 dB/octave), 100-300 Hz (PSD(M)c = 0.05 g ² /Hz × (mass + 20 kg)/(mass + 1 kg), 300-2000 Hz (-5 dB/octave)
7	Final Entanglement Quality	See Task 1

Conclusions

- Aspects of space-suitable design
 - Tolerancing
 - Materials
 - Integration technologies
- Testing for space environments
 - Expected in late spring 2017



**Fraunhofer IOF –
Research for the Future**